10-EY12PMA015M7-L186A78T
10-E212PMA015M7-L186A78Z
datasheet

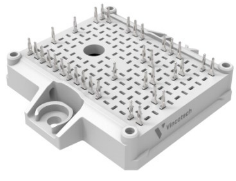
Vincotech

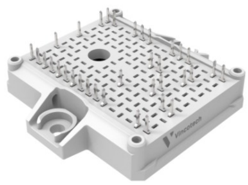
***flow*PIM E2** **1200 V / 15 A**

Features

- IGBT M7 with low V_{CEsat} and improved EMC behavior
- Standard industrial housing
- Optimized $R_{th(j-s)}$ with Phase Change Material
- Built-in NTC

flow E2 12 mm housing

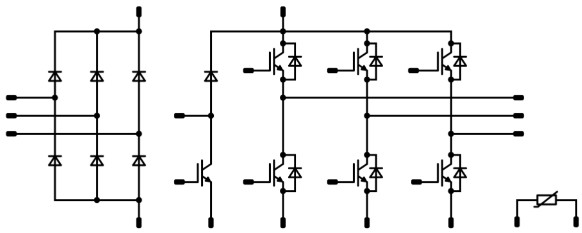

Press-fit pin


Solder pin

Target applications

- Industrial Drives

Schematic



Types

- 10-EY12PMA015M7-L186A78T
- 10-E212PMA015M7-L186A78Z

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C	$T_j = T_{jmax}$ T_s = 80 °C	21	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	64	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Inverter Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$	T_s = 80 °C	21	A
Repetitive peak forward current	I_{FRM}	T_j limited by T_{jmax}		30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	51	W
Maximum junction temperature	T_{jmax}			175	°C
Brake Switch					
Collector-emitter voltage	V_{CES}			1200	V
Collector current	I_C	$T_j = T_{jmax}$	T_s = 80 °C	21	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}		30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	64	W
Gate-emitter voltage	V_{GES}			±20	V
Maximum junction temperature	T_{jmax}			175	°C
Brake Diode					
Peak repetitive reverse voltage	V_{RRM}			1200	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$	T_s = 80 °C	14	A
Repetitive peak forward current	I_{FRM}	T_j limited by T_{jmax}		20	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	43	W
Maximum junction temperature	T_{jmax}			175	°C
Rectifier Diode					
Peak repetitive reverse voltage	V_{RRM}			1600	V
Continuous (direct) forward current	I_F	$T_j = T_{jmax}$	T_s = 80 °C	47	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave t_p = 10 ms	T_j = 150 °C	270	A
Surge current capability	I^2t			370	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$	T_s = 80 °C	58	W
Maximum junction temperature	T_{jmax}			150	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Module Properties					
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{jop}			-40…(T_{jmax} - 25)	°C
Isolation Properties					
Isolation voltage	V_{isol}	DC Test Voltage*	t_p = 2 s	6000	V
		AC Voltage	t_p = 1 min	2500	V
Creepage distance				min. 12,7	mm
Clearance		Press-fit pin / Solder pin		8,83 / 8,85	mm
Comparative Tracking Index	CTI			≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,0015	25	5,4	6,0	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,70 1,95 2,01	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}							120		
Reverse transfer capacitance	C_{res}							34		
Gate charge	Q_g		15	600	15	25		110		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,49		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	15	25 125 150		196 191 190		ns
Rise time	t_r					25 125 150		60 63 64		
Turn-off delay time	$t_{d(off)}$					25 125 150		181 206 211		
Fall time	t_f					25 125 150		95 113 114		
Turn-on energy (per pulse)*	E_{on}	Q_{rFWD} = 1,5 µC Q_{rFWD} = 2,5 µC Q_{rFWD} = 2,7 µC				25 125 150		1,69 2,11 2,21		mWs
Turn-off energy (per pulse)*	E_{off}					25 125 150		0,987 1,33 1,41		

* Ls = 10 nH

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				15	25 125 150		1,63 1,74 1,73	2,1	V
Reverse leakage current	I_R			1200		25			30	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,88		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 181 A/µs di/dt = 205 A/µs di/dt = 175 A/µs	±15	600	15	25 125 150		9 11 11		A
Reverse recovery time	t_{rr}					25 125 150		286 422 471		ns
Recovered charge	Q_r					25 125 150		1,50 2,46 2,68		µC
Reverse recovered energy	E_{rec}					25 125 150		0,497 0,913 1,00		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		77 49 44		A/µs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] / V_{GS} [V]	V_{CE} [V] / V_{DS} [V] / V_F [V]	I_C [A] / I_D [A] / I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Brake Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,0015	25	5,4	6,0	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,70 1,95 2,01	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}		0	10		25		120		pF
Reverse transfer capacitance	C_{res}		0	10		25		34		pF
Gate charge	Q_g		15	600	15	25		110		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,49		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	0 / 15	600	15	25 125 150		300 262 253		ns
Rise time	t_r	R_{gon} = 32 Ω R_{goff} = 32 Ω	0 / 15	600	15	25 125 150		194 205 209		ns
Turn-off delay time	$t_{d(off)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	0 / 15	600	15	25 125 150		388 428 438		ns
Fall time	t_f	R_{gon} = 32 Ω R_{goff} = 32 Ω	0 / 15	600	15	25 125 150		67 87 89		ns
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,1 µC Q_{rFWD} = 1,8 µC Q_{rFWD} = 2 µC	0 / 15	600	15	25 125 150		2,50 3,01 3,19		mWs
Turn-off energy (per pulse)	E_{off}		0 / 15	600	15	25 125 150		1,12 1,44 1,54		mWs

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Value Min	Typ	Max	Unit
Brake Diode										
Static										
Forward voltage	V_F				10	25 125 150		1,61 1,69 1,69	2,1	V
Reverse leakage current	I_R			1200		25			25	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j\text{-}s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,19		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 74 A/µs di/dt = 65 A/µs di/dt = 62 A/µs	0 / 15	600	15	25 125 150		6 7 7		A
Reverse recovery time	t_{rr}					25 125 150		317 473 542		ns
Recovered charge	Q_r					25 125 150		1,11 1,78 2,04		µC
Reverse recovered energy	E_{rec}					25 125 150		0,368 0,644 0,753		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		40 28 24		A/µs
Rectifier Diode										
Static										
Forward voltage	V_F				35	25 125		1,17 1,13		V
Reverse leakage current	I_R			1600		25			50	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j\text{-}s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,20		K/W

Characteristic Values

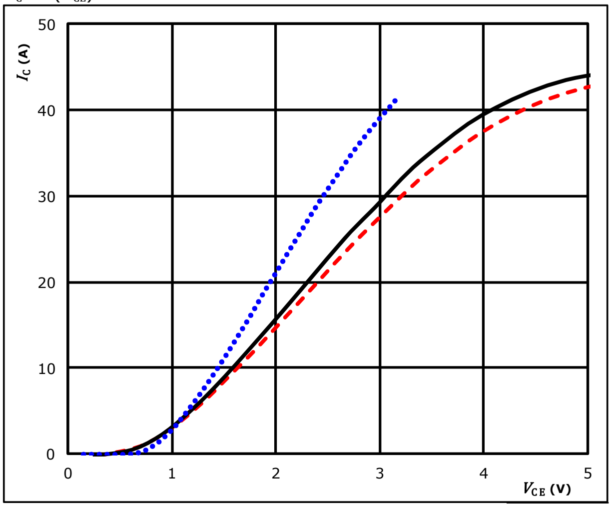
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Rated resistance	R					25		5		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 493 Ω				100	-5		+5	%
Power dissipation	P					25		245		mW
Power dissipation constant						25		1,4		mW/K
B-value	$B_{(25/50)}$	Tol. ±2 %				25		3375		K
B-value	$B_{(25/100)}$	Tol. ±2 %				25		3437		K
Vincotech NTC Reference									K	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

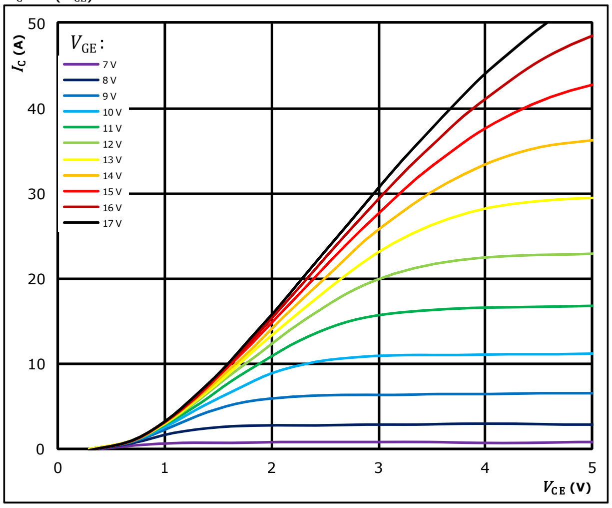


t_p =	250	µs		25 °C	············
V_{GE} =	15	V	T_j:	125 °C	———
				150 °C	– – – –

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



t_p = 250 µs

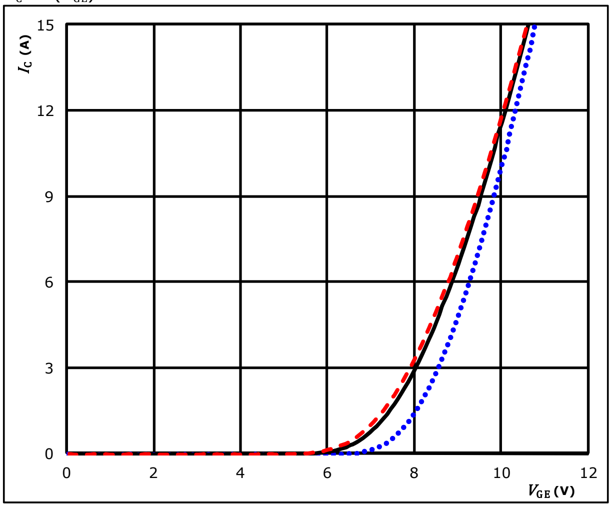
T_j = 150 °C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

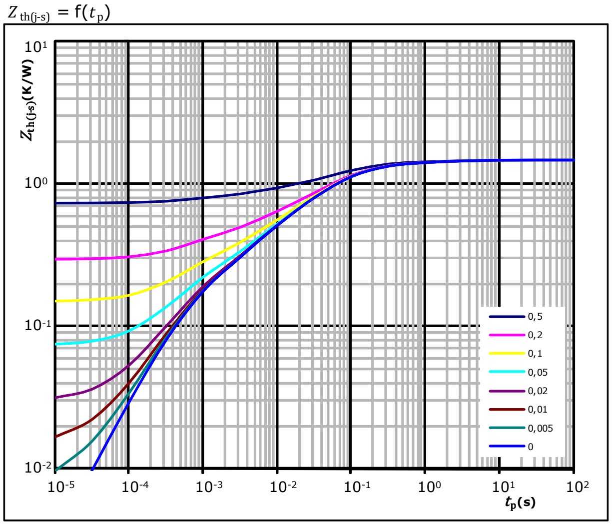


t_p =	100	µs		25 °C	············
V_{CE} =	10	V	T_j:	125 °C	———
				150 °C	– – – –

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j\text{-}s)} = f(t_p)$



D = t_p / T

$R_{th(j\text{-}s)}$ = 1,49 K/W

IGBT thermal model values

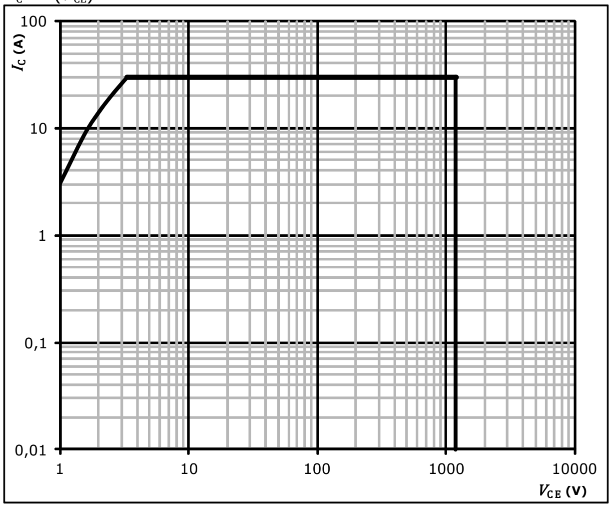
R (K/W)	τ (s)
4,90E-02	3,61E+00
1,10E-01	6,54E-01
4,70E-01	1,09E-01
4,98E-01	2,97E-02
2,21E-01	4,73E-03
1,37E-01	5,51E-04

Inverter Switch Characteristics

figure 5.	**IGBT**

Safe operating area

$I_C = f(V_{CE})$



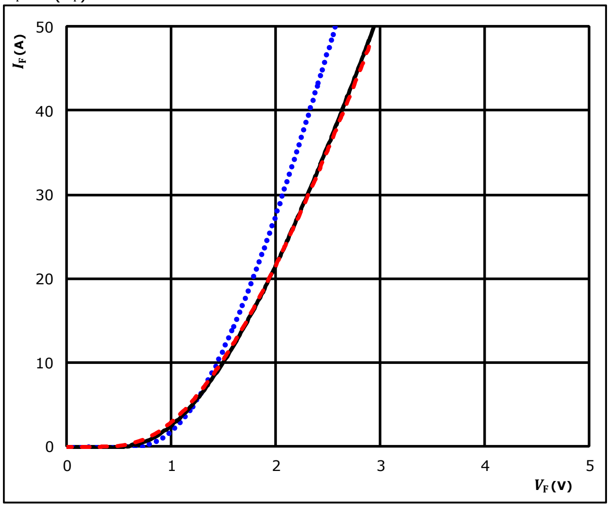
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



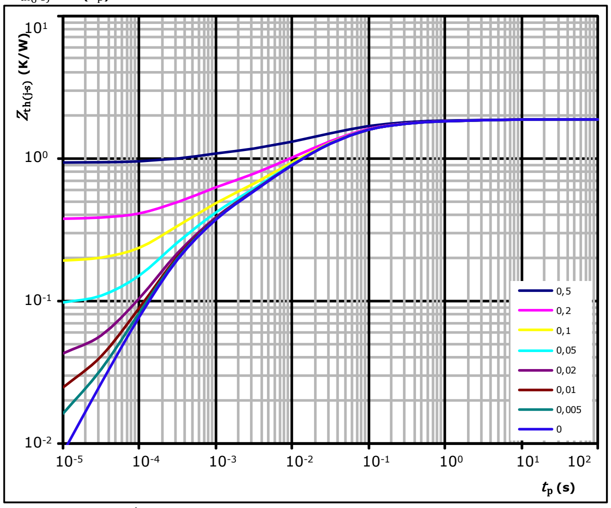
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,88 K/W

FWD thermal model values

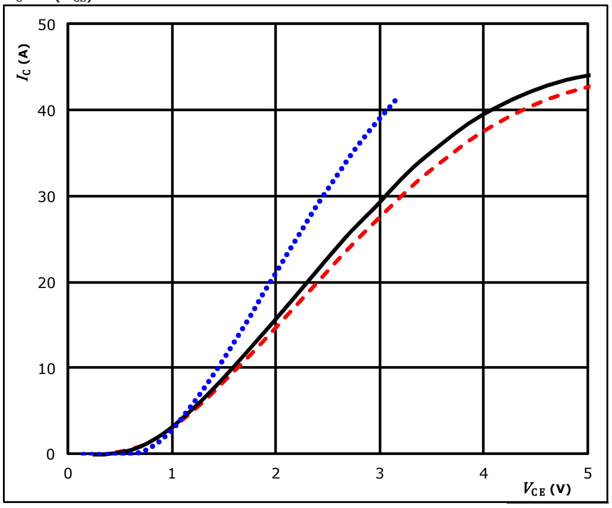
R (K/W)	τ (s)
7,31E-02	2,45E+00
1,93E-01	2,55E-01
6,27E-01	4,97E-02
4,83E-01	1,15E-02
2,56E-01	2,33E-03
2,42E-01	3,41E-04

Brake Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

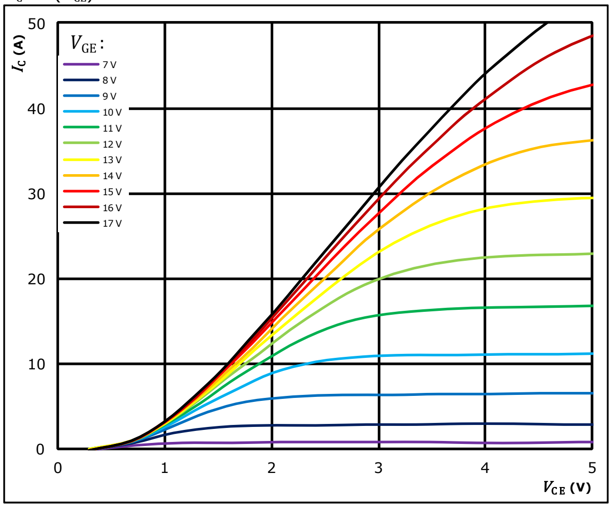


t_p =	250	µs		25 °C	············
V_{GE} =	15	V	T_j:	125 °C	———
				150 °C	– – –

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$



t_p = 250 µs

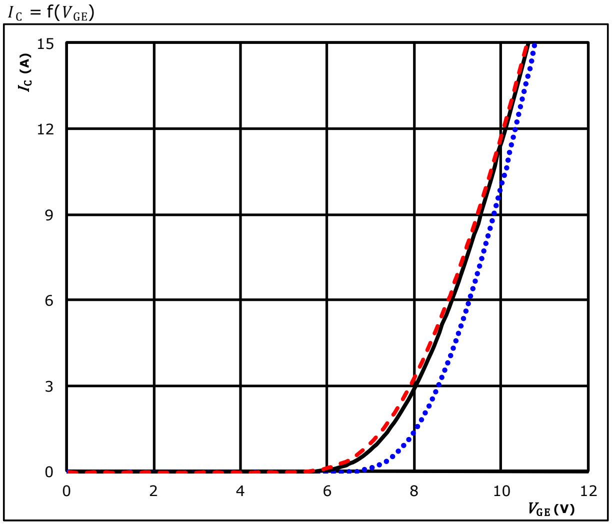
T_j = 150 °C

V_{GE} from 7 V to 17 V in steps of 1 V

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

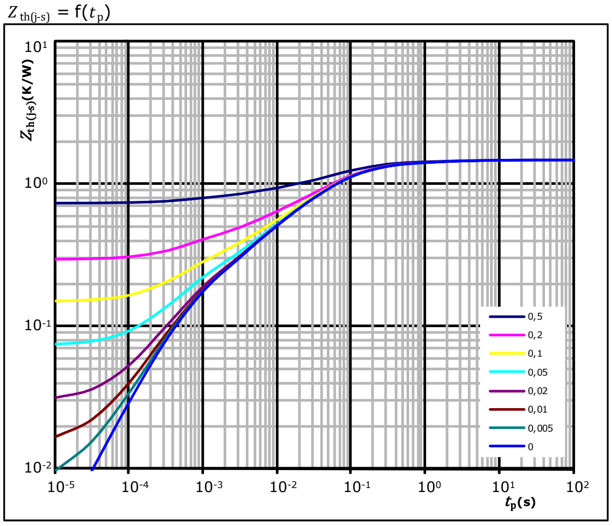


t_p =	100	µs		25 °C	············
V_{CE} =	10	V	T_j:	125 °C	———
				150 °C	– – –

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 1,49 K/W

IGBT thermal model values

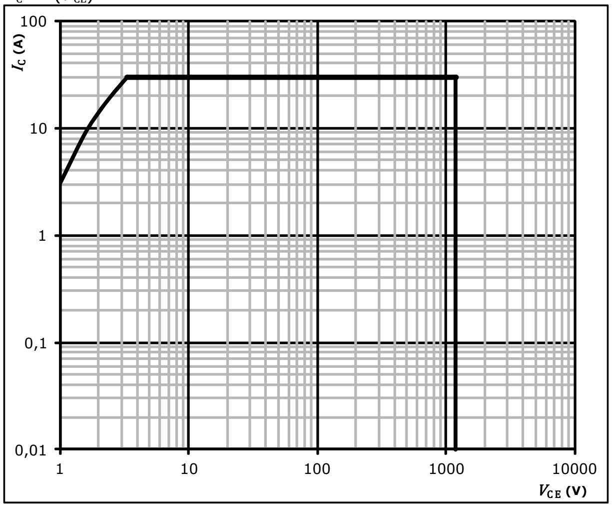
R (K/W)	τ (s)
4,90E-02	3,61E+00
1,10E-01	6,54E-01
4,70E-01	1,09E-01
4,98E-01	2,97E-02
2,21E-01	4,73E-03
1,37E-01	5,51E-04

Brake Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



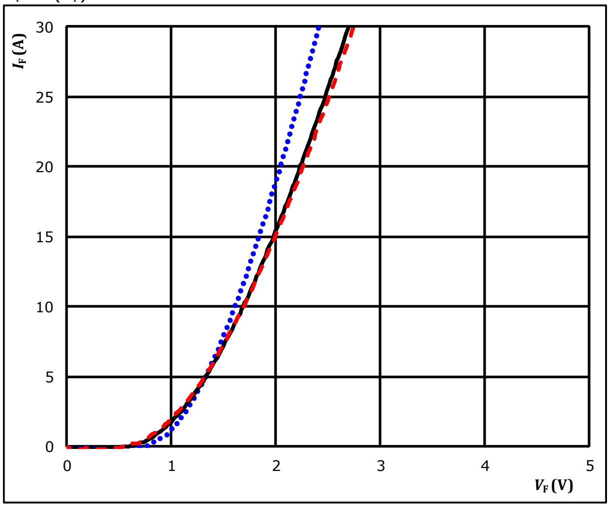
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Brake Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



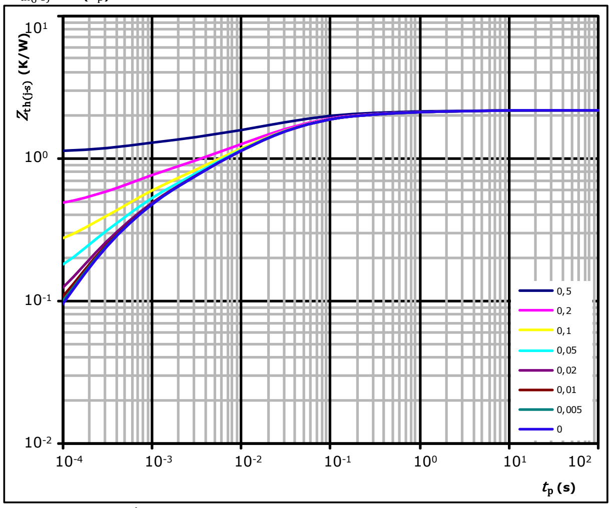
t_p = 250 µs

T_j: 25 °C · 125 °C · 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 2,19 K/W

FWD thermal model values

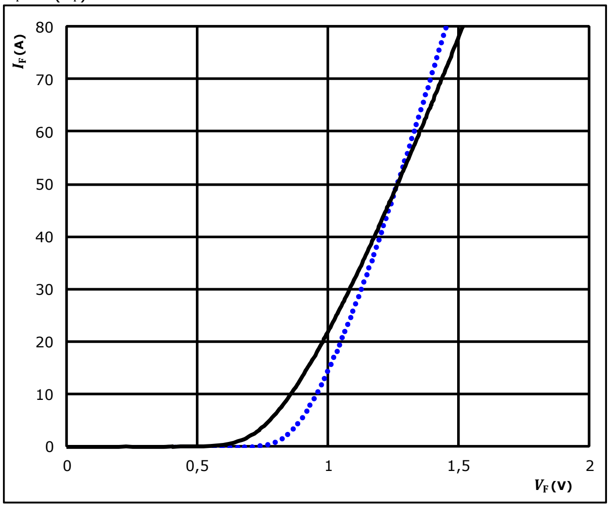
R (K/W)	τ (s)
8,09E-02	3,20E+00
2,08E-01	2,82E-01
6,85E-01	4,41E-02
5,92E-01	1,02E-02
3,27E-01	2,02E-03
2,95E-01	3,64E-04

Rectifier Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



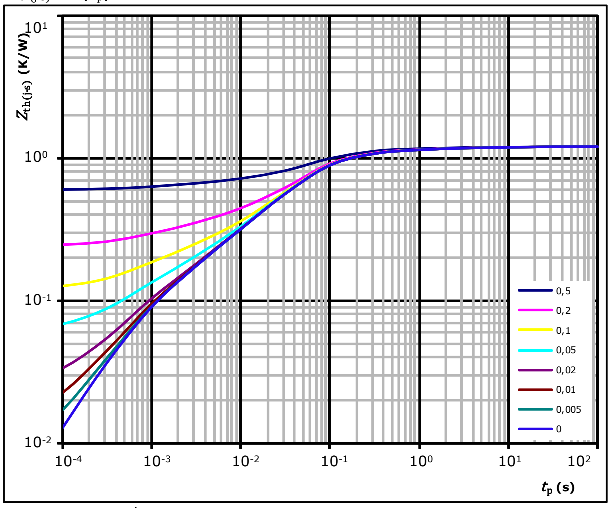
t_p = 250 µs

T_j: 25 °C (dotted), 125 °C (solid)

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,20 K/W

FWD thermal model values

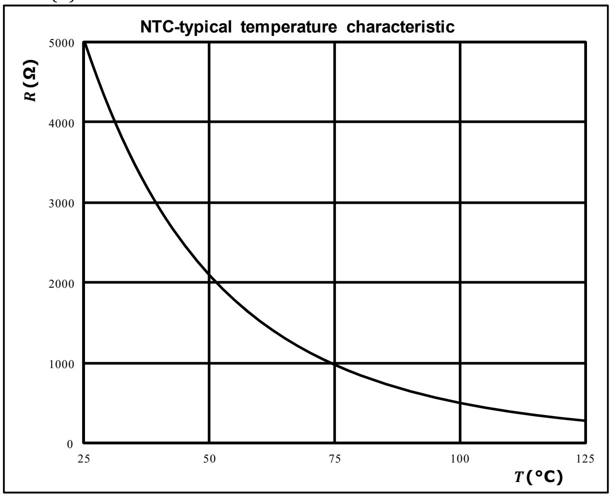
R (K/W)	τ (s)
3,54E-02	9,31E+00
8,09E-02	9,99E-01
2,12E-01	1,71E-01
6,76E-01	4,85E-02
1,19E-01	5,88E-03
7,98E-02	8,33E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic as a function of temperature

$R = f(T)$

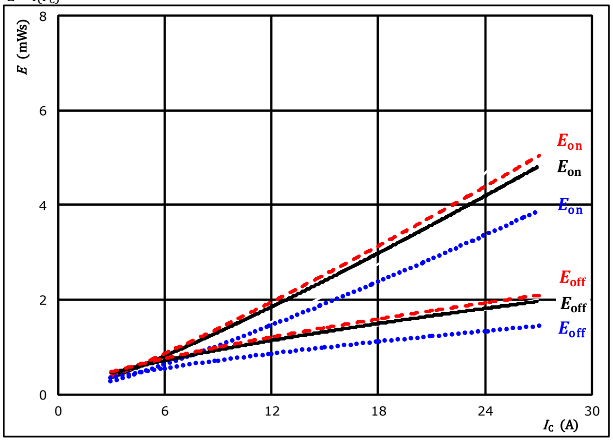


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



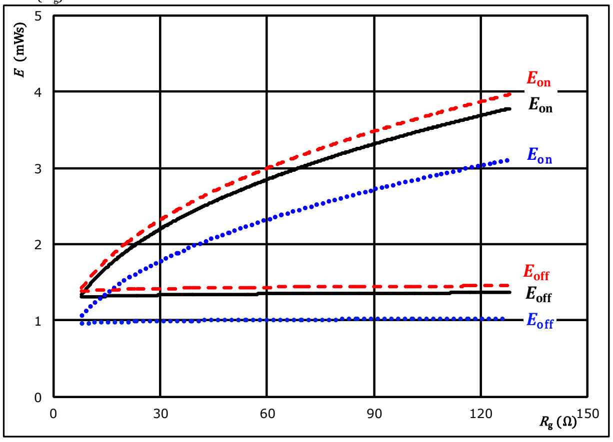
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	±15	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed
R_{goff} =	32	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



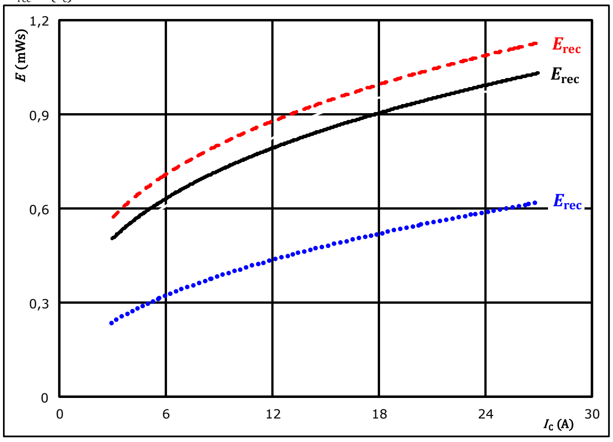
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	±15	V		125 °C	solid
I_C =	15	A		150 °C	dashed

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_c)$



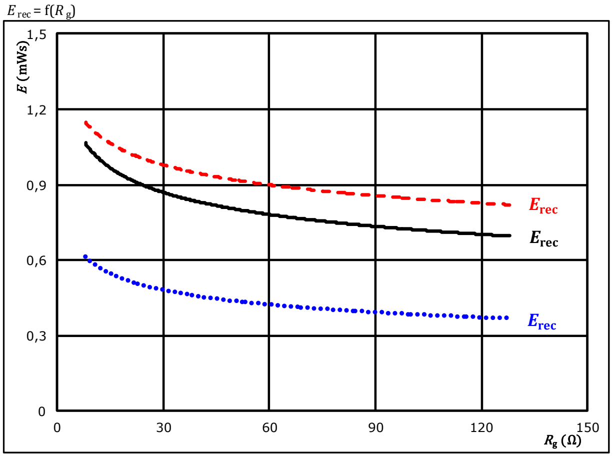
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	±15	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

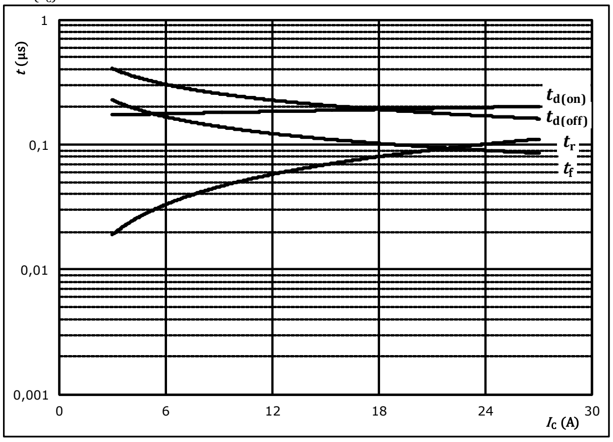
V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	±15	V		125 °C	solid
I_C =	15	A		150 °C	dashed

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



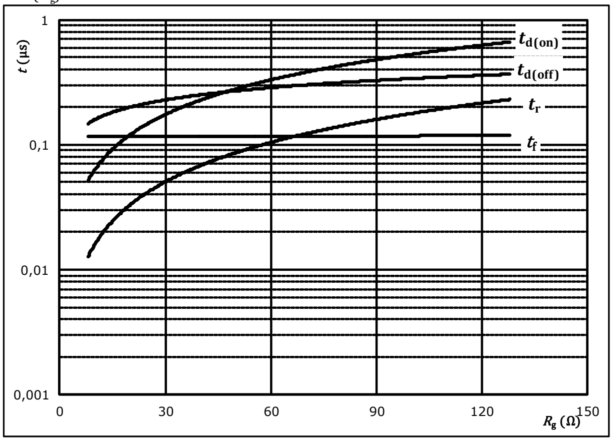
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



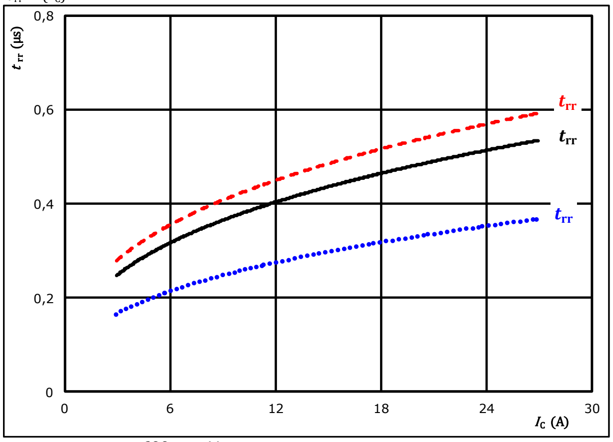
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

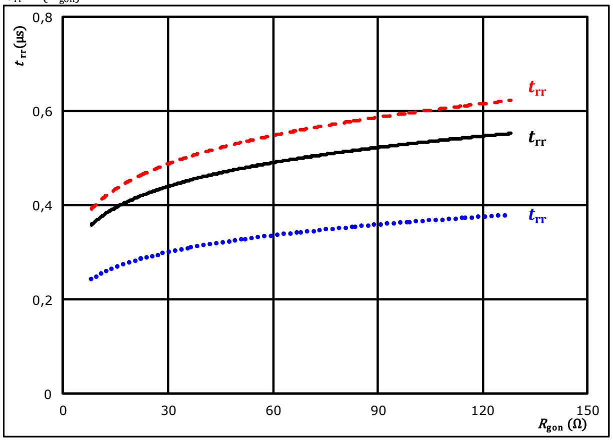


At						
V_{CE} =	600	V		25 °C	···········
V_{GE} =	±15	V	T_j:	125 °C	———
R_{gon} =	32	Ω		150 °C	– – –

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



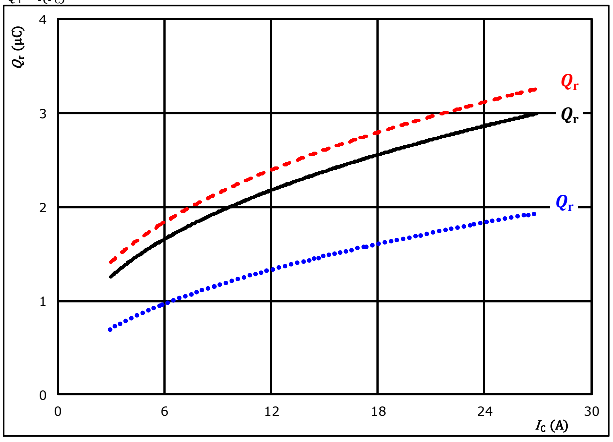
At						
V_{CE} =	600	V		25 °C	···········
V_{GE} =	±15	V	T_j:	125 °C	———
I_C =	15	A		150 °C	– – –

Inverter Switching Characteristics

figure 9. FWD

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

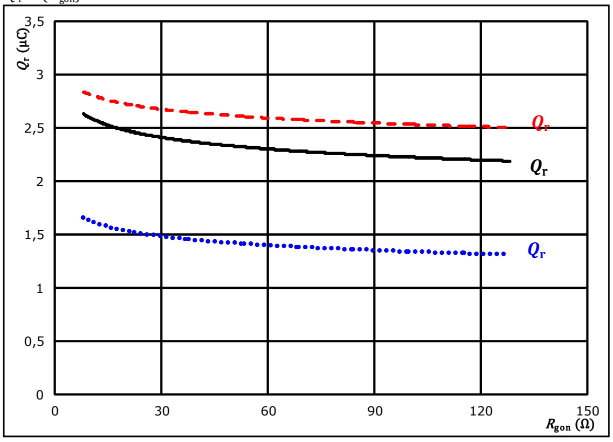


At					
V_{CE} =	600	V		25 °C	···········
V_{GE} =	±15	V	T_j:	125 °C	———
R_{gon} =	32	Ω		150 °C	- - -

figure 10. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

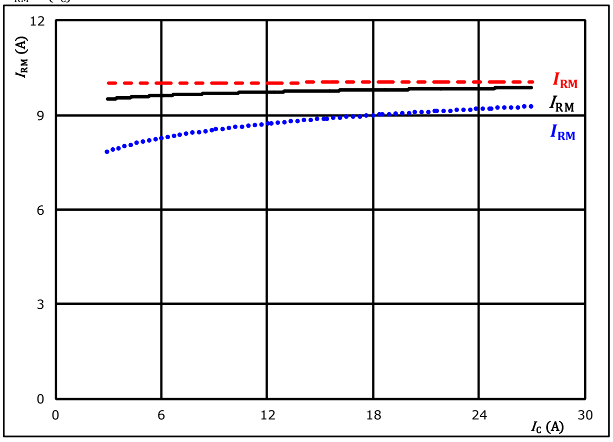


At					
V_{CE}=	600	V		25 °C	···········
V_{GE} =	±15	V	T_j:	125 °C	———
I_C=	15	A		150 °C	- - -

figure 11. FWD

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

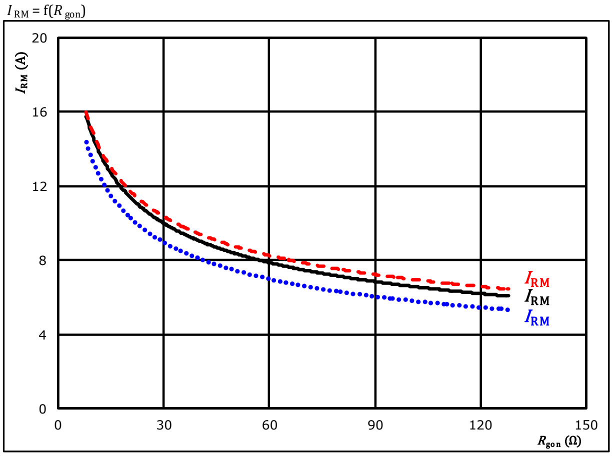


At					
V_{CE} :	600	V		25 °C	···········
V_{GE} =	±15	V	T_j:	125 °C	———
R_{gon} =	32	Ω		150 °C	- - -

figure 12. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



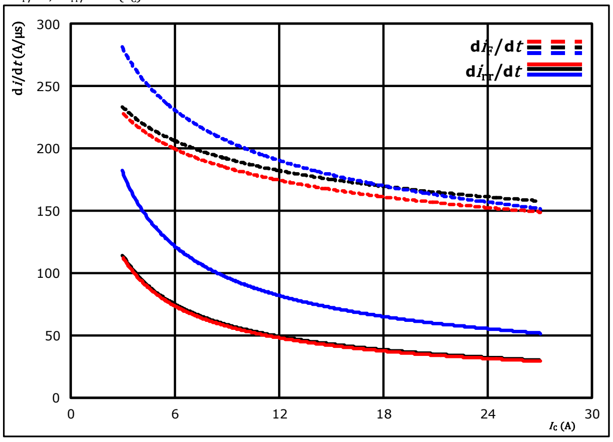
At					
V_{CE} =	600	V		25 °C	···········
V_{GE} =	±15	V	T_j:	125 °C	———
I_C =	15	A		150 °C	- - -

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$



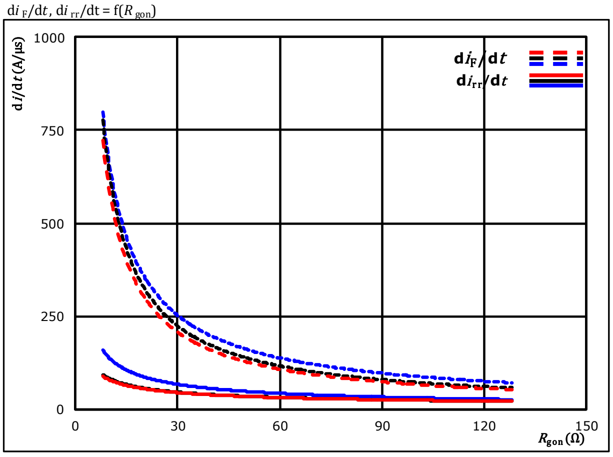
At

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	32	Ω		150 °C

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$



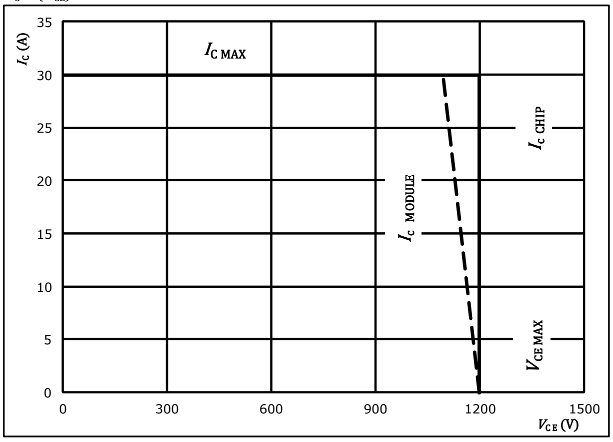
At

V_{CE} =	600	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	15	A		150 °C

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	175	°C
R_{gon} =	32	Ω
R_{goff} =	32	Ω

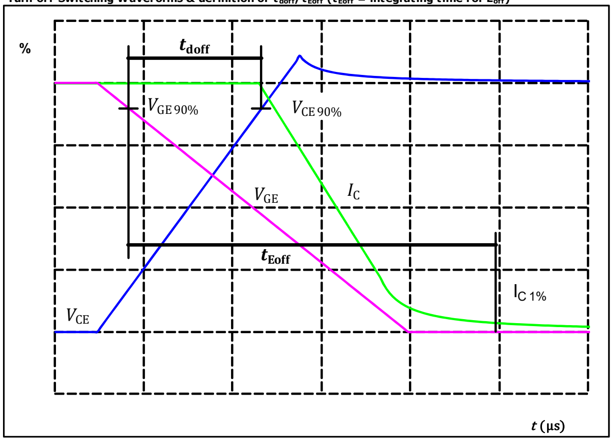
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. **IGBT**

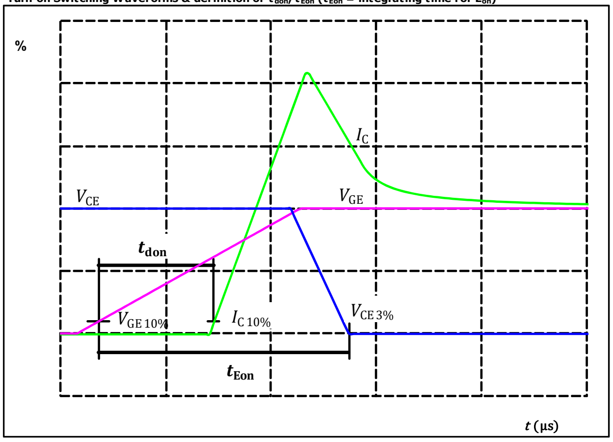
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



V_{GE}(0%) =	-15	V
V_{GE}(100%) =	15	V
V_C(100%) =	600	V
I_C(100%) =	15	A
t_{doff} =	206	ns

figure 2. **IGBT**

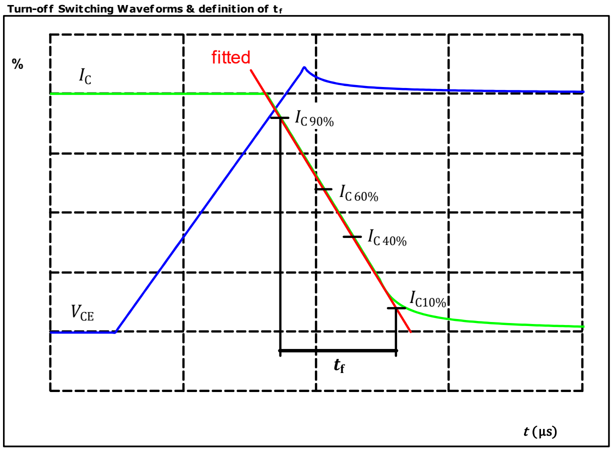
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



V_{GE}(0%) =	-15	V
V_{GE}(100%) =	15	V
V_C(100%) =	600	V
I_C(100%) =	15	A
t_{don} =	191	ns

figure 3. **IGBT**

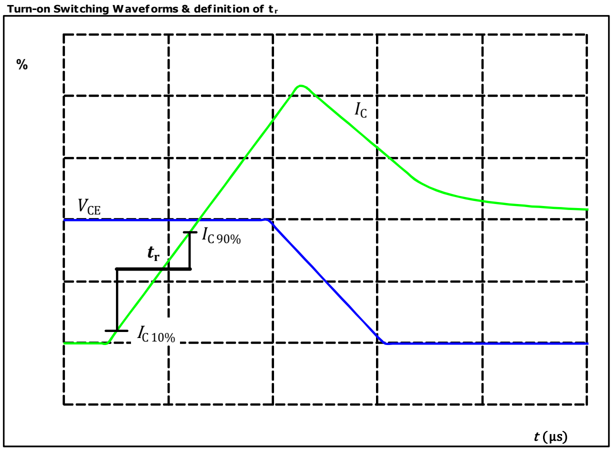
Turn-off Switching Waveforms & definition of t_f



V_C(100%) =	600	V
I_C(100%) =	15	A
t_f =	113	ns

figure 4. **IGBT**

Turn-on Switching Waveforms & definition of t_r

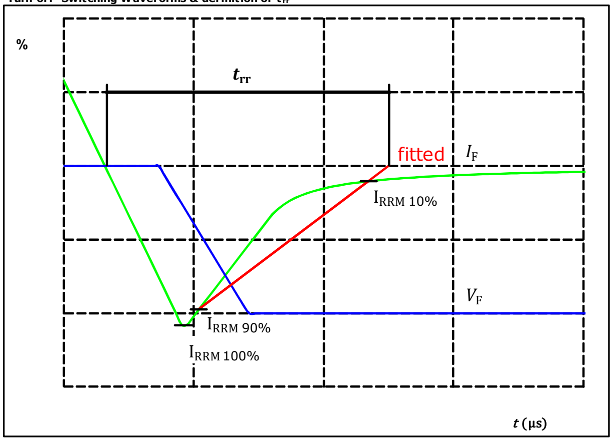


V_C(100%) =	600	V
I_C(100%) =	15	A
t_r =	63	ns

Inverter Switching Characteristics

figure 5. **FWD**

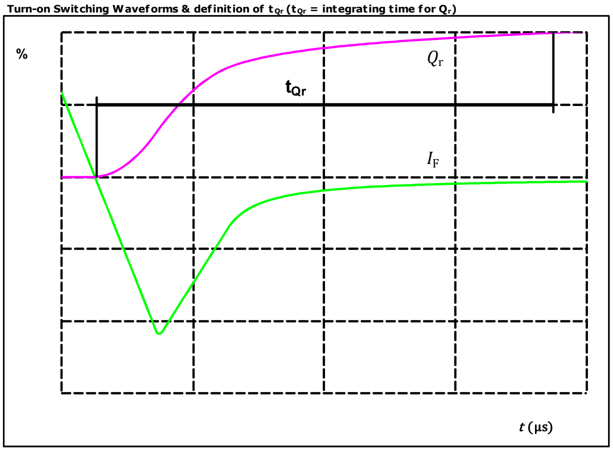
Turn-off Switching Waveforms & definition of t_{rr}



V_F (100%) =	600	V
I_F (100%) =	15	A
I_{RRM} (100%) =	11	A
t_{rr} =	422	ns

figure 6. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



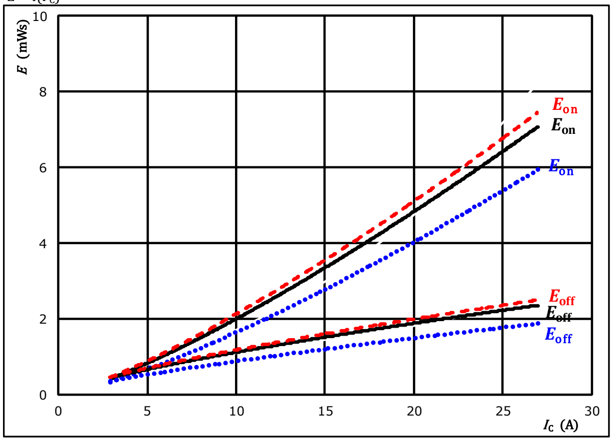
I_F (100%) =	15	A
Q_r (100%) =	2,46	µC

Brake Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



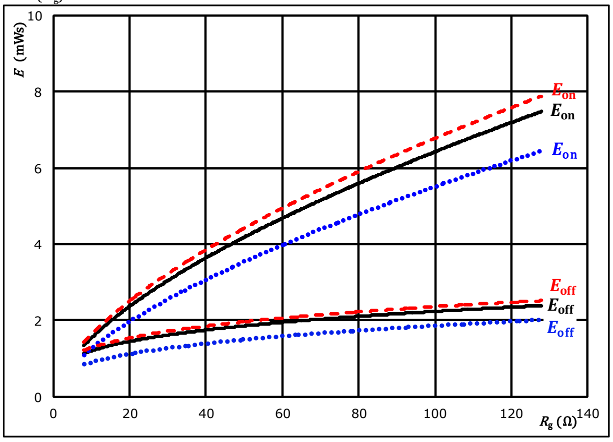
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed
R_{goff} =	32	Ω			

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



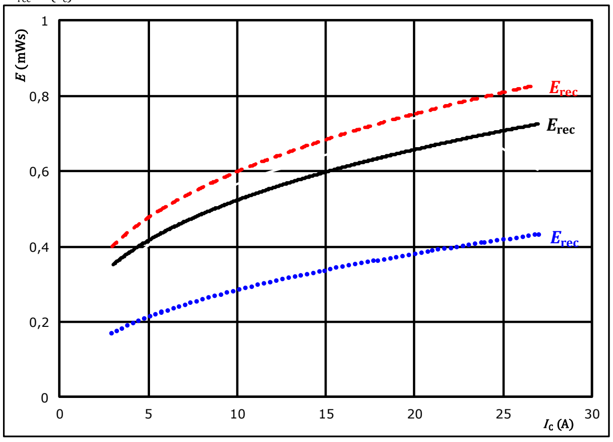
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
I_C =	15	A		150 °C	dashed

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_c)$



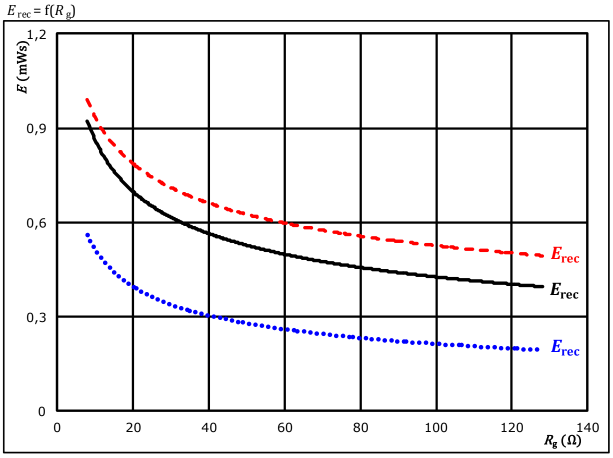
With an inductive load at

V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

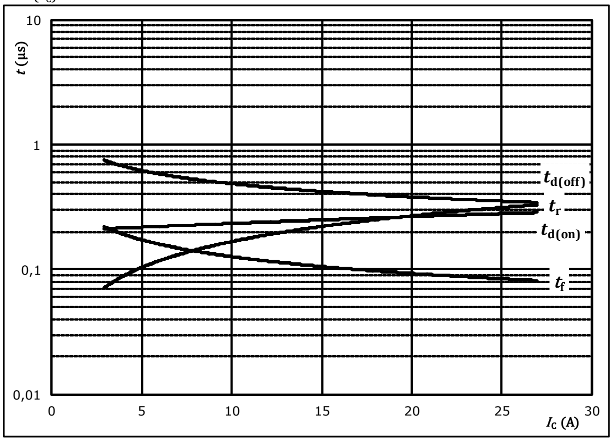
V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
I_C =	15	A		150 °C	dashed

Brake Switching Characteristics

figure 5. IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



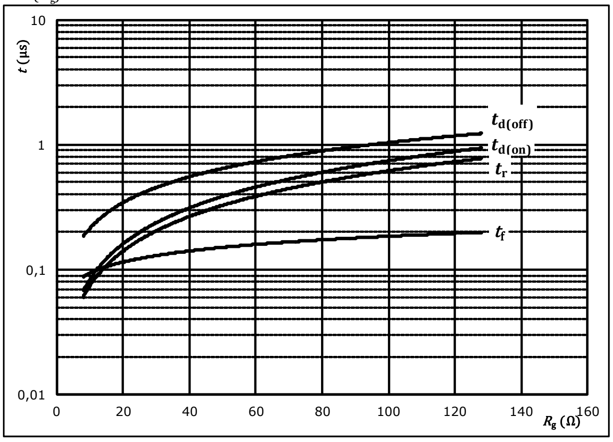
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	0 / 15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. IGBT

Typical switching times as a function of gate resistor

$t = f(R_g)$



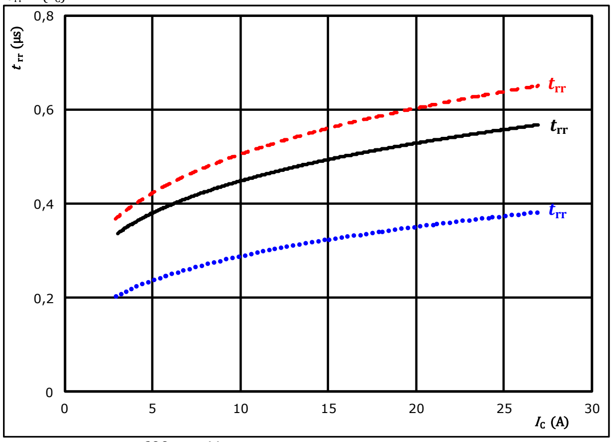
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	0 / 15	V
I_C =	15	A

figure 7. FWD

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

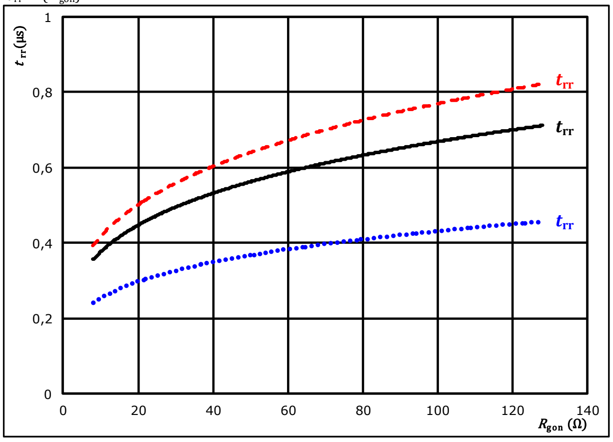


At V_{CE} = 600 V, V_{GE} = 0 / 15 V, R_{gon} = 32 Ω; T_j: 25 °C (dotted), 125 °C (solid), 150 °C (dashed)

figure 8. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



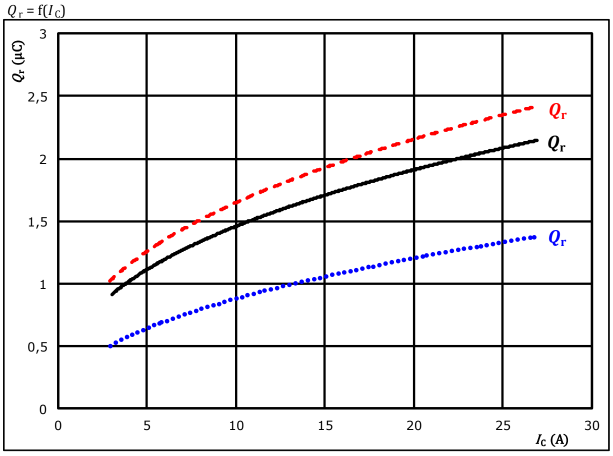
At V_{CE} = 600 V, V_{GE} = 0 / 15 V, I_C = 15 A; T_j: 25 °C (dotted), 125 °C (solid), 150 °C (dashed)

Brake Switching Characteristics

figure 9. FWD

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

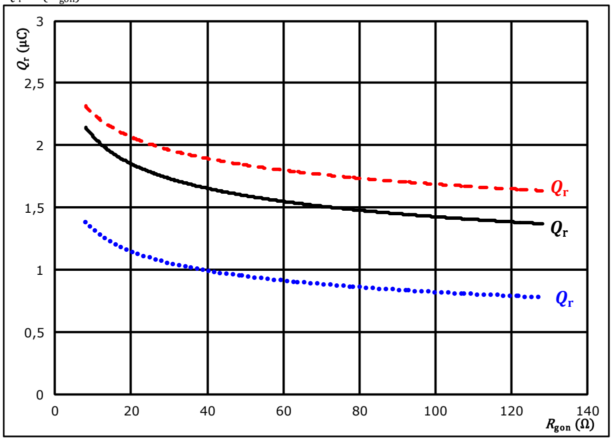


At					
V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed

figure 10. FWD

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

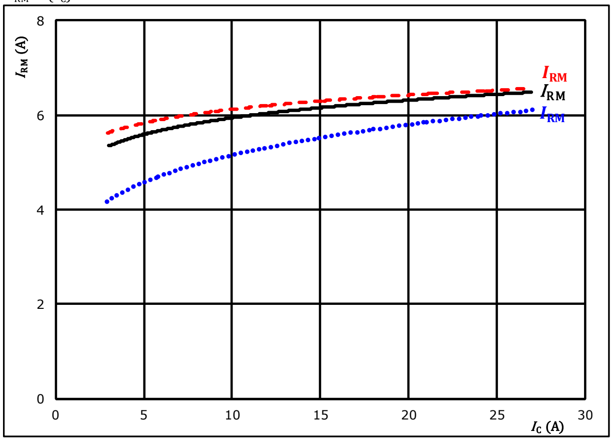


At					
V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
I_C =	15	A		150 °C	dashed

figure 11. FWD

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

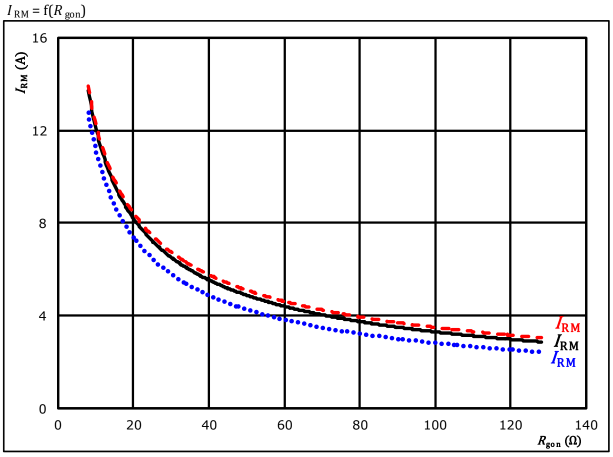


At					
V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
R_{gon} =	32	Ω		150 °C	dashed

figure 12. FWD

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



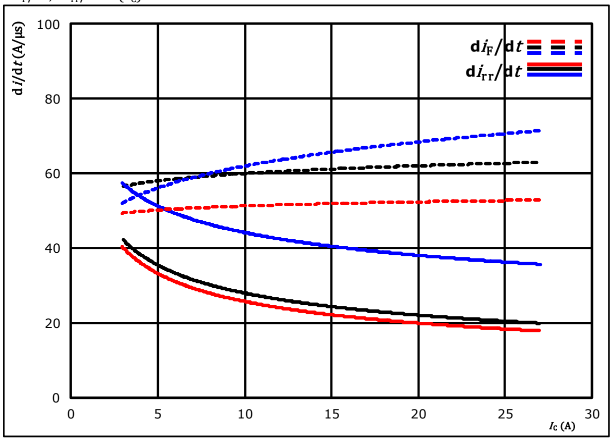
At					
V_{CE} =	600	V	T_j:	25 °C	dotted
V_{GE} =	0 / 15	V		125 °C	solid
I_C =	15	A		150 °C	dashed

Brake Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$

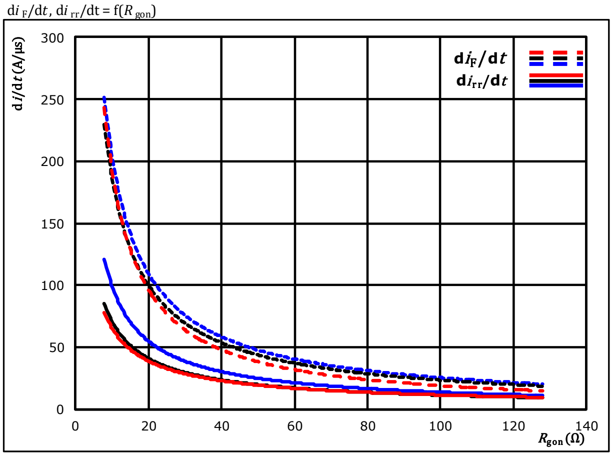


At						
	V_{CE} =	600	V		25	°C
	V_{GE} =	0 / 15	V	T_j:	125	°C
	R_{gon} =	32	Ω		150	°C

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$

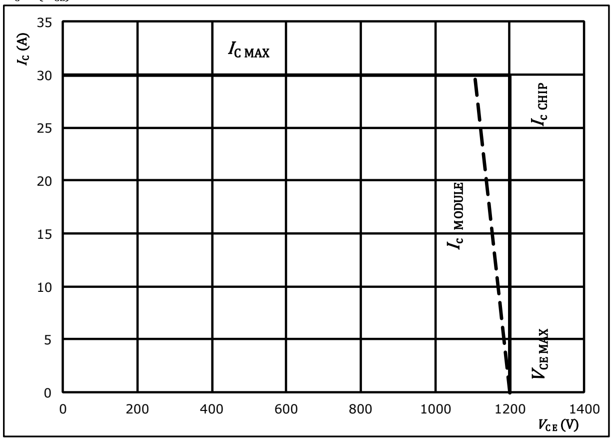


At						
	V_{CE} =	600	V		25	°C
	V_{GE} =	0 / 15	V	T_j:	125	°C
	I_C=	15	A		150	°C

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



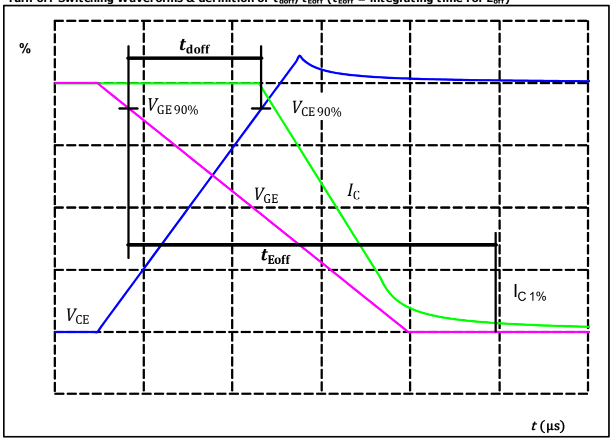
At			
	T_j =	125	°C
	R_{gon} =	32	Ω
	R_{goff} =	32	Ω

Brake Switching Definitions

General conditions		
T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

figure 1. IGBT

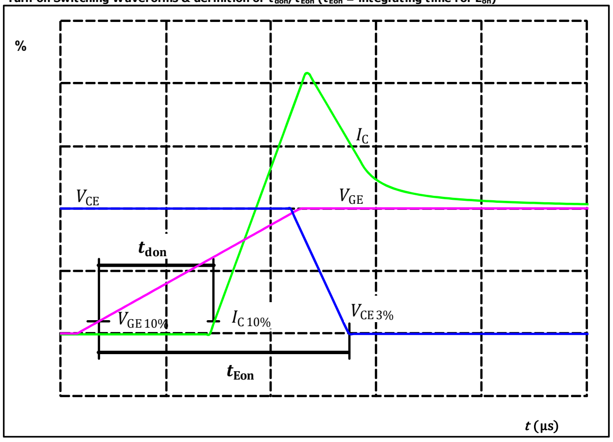
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	0	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{doff} =	428	ns

figure 2. IGBT

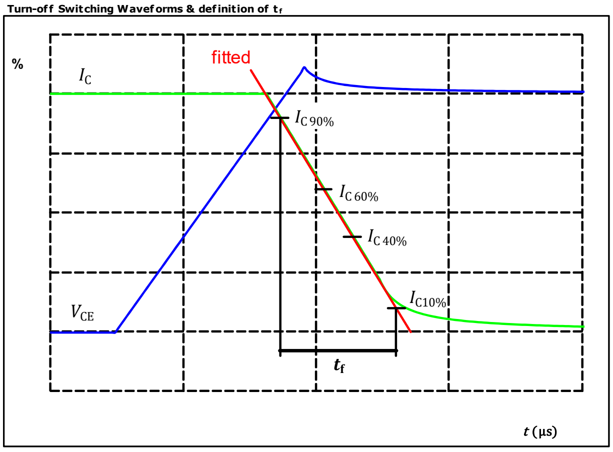
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	0	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{don} =	262	ns

figure 3. IGBT

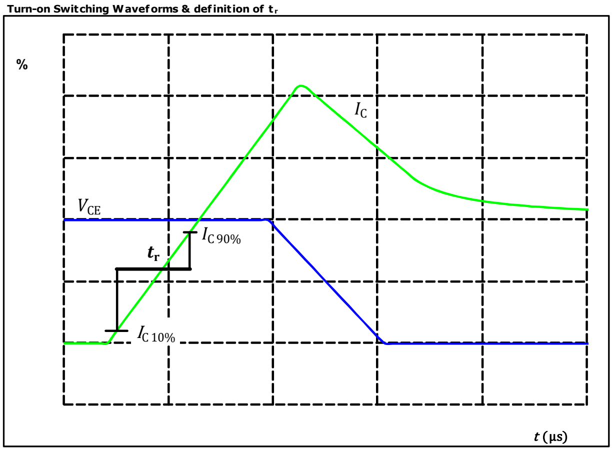
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_f =	87	ns

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r



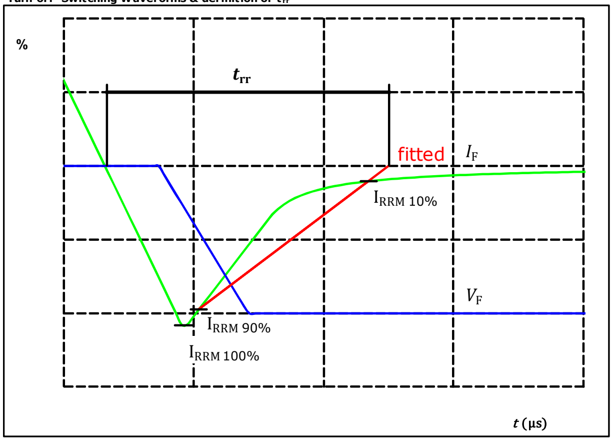
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_r =	205	ns

10-EY12PMA015M7-L186A78T
10-E212PMA015M7-L186A78Z
datasheet

Brake Switching Characteristics

figure 5. **FWD**

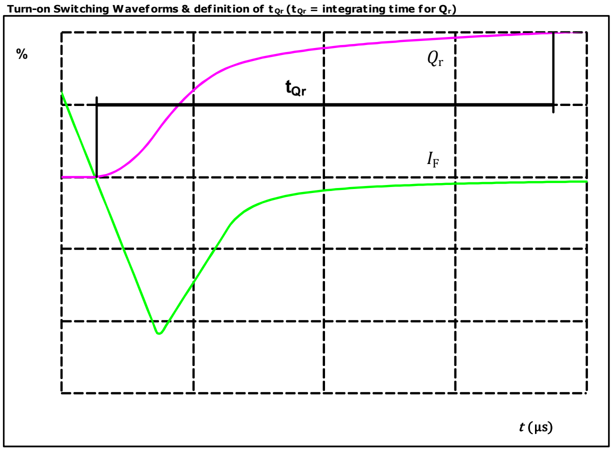
Turn-off Switching Waveforms & definition of t_{rr}



V_F (100%) =	600	V
I_F (100%) =	15	A
I_{RRM} (100%) =	7	A
t_{rr} =	473	ns

figure 6. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F (100%) =	15	A
Q_r (100%) =	1,78	µC

Ordering Code & Marking

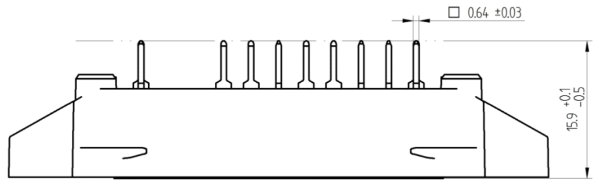
Version	Ordering Code
without thermal paste 12 mm housing with press-fit pins	10-EY12PMA015M7-L186A78T
with thermal paste 12 mm housing with press-fit pins	10-EY12PMA015M7-L186A78T-/3/
without thermal paste 12 mm housing with Solder pins	10-E212PMA015M7-L186A78Z
with thermal paste 12 mm housing with Solder pins	10-E212PMA015M7-L186A78Z-/3/

	Name		Date code	UL & VIN	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	Lot number	Serial	Date code		
Datamatrix	TTTTTTTVV	LLLLL	SSSS	WWYY		

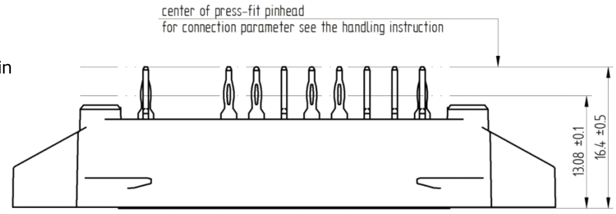
Outline

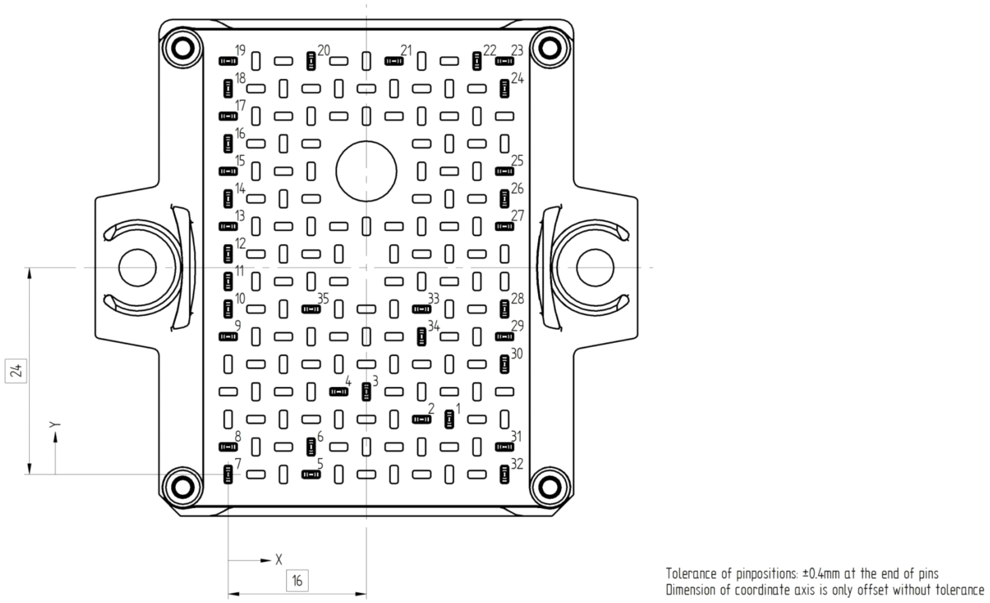
Pin table			
Pin	X	Y	Function
1	25,6	6,4	ACIn2
2	22,4	6,4	ACIn2
3	16	9,6	ACIn1
4	12,8	9,6	ACIn1
5	9,6	0	DC+Rect
6	9,6	3,2	DC+Rect
7	0	0	DC-Rect
8	0	3,2	DC-Rect
9	0	16	G27
10	0	19,2	DC-Br
11	0	22,4	G11
12	0	25,6	DC-1
13	0	28,8	DC-1
14	0	32	G13
15	0	35,2	DC-2
16	0	38,4	DC-2
17	0	41,6	G15
18	0	44,8	DC-3
19	0	48	DC-3
20	9,6	48	Therm1
21	19,2	48	Therm2
22	28,8	48	G16
23	32	48	Ph3
24	32	44,8	Ph3
25	32	35,2	G14
26	32	32	Ph2
27	32	28,8	Ph2
28	32	19,2	G12
29	32	16	Ph1
30	32	12,8	Ph1
31	32	3,2	ACIn3
32	32	0	ACIn3
33	22,4	19,2	DC+Inv
34	22,4	16	DC+Inv
35	9,6	19,2	Br

Solder pin

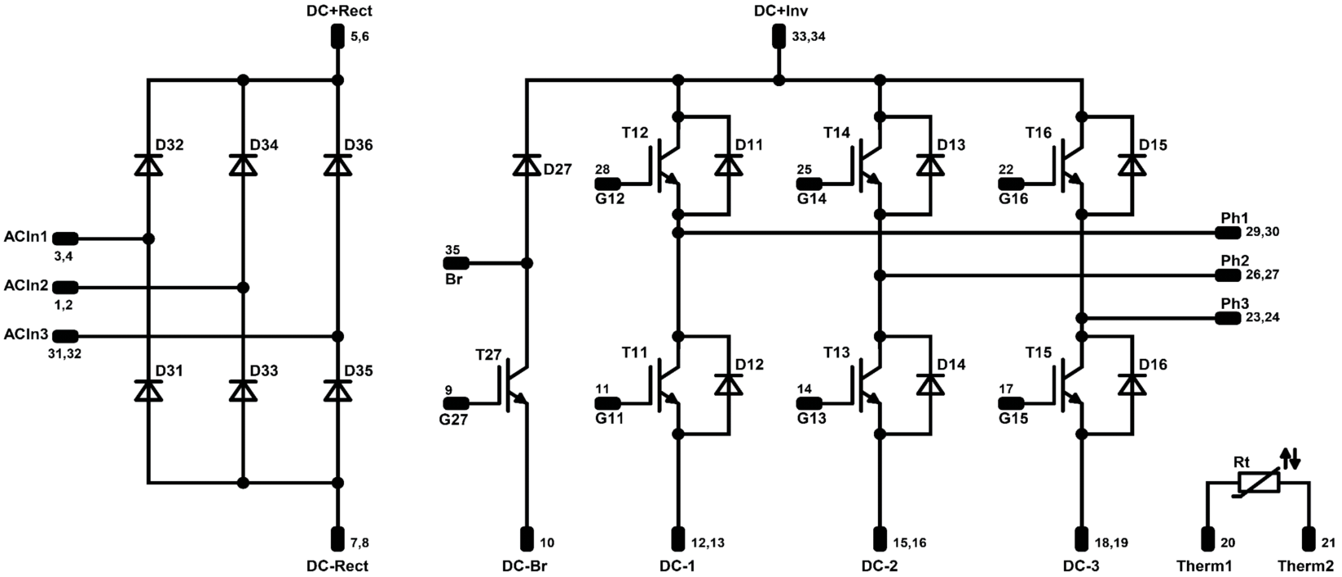


Press-fit pin





Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	15 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	15 A	Inverter Diode	
T27	IGBT	1200 V	15 A	Brake Switch	
D27	FWD	1200 V	10 A	Brake Diode	
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	35 A	Rectifier Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* E2 packages see vincotech.com website.

Package data
Package data for *flow* E2 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-Ex12PMA015M7-L186A78x-D3-14	30 May. 2019	Correction of I_c/I_f values Outline updated	1,2 28